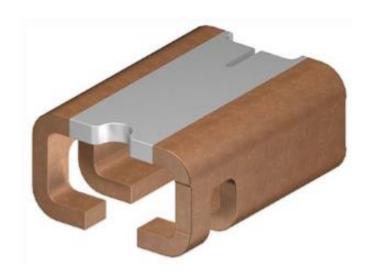




# **High Power Shunt Resistor**





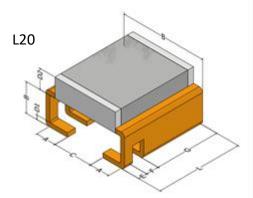
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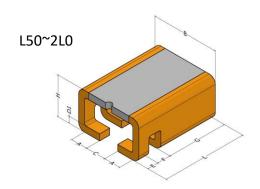
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#### Scope

This specification applies for metal type current shunt resistor.

#### Dim





Туре	Dimensions(mm)									
(inch size)	L	В	н	E	F	G(Ref)	Α	D1/D2	С	
SR1216	2 01+0 20	2 0010 45	2 240 45	0.5010.45	0.6010.15	2.70	1.05	0.20/0.70	0.05+0.45	
L20	3.81±0.30	3.00±0.15	2.2±0.15	0.50±0.15	0.60±0.15	2.70	1.05	0.30/0.70	0.95±0.15	
SR1216	2 04 10 20	2 0010 45	4 0010 45	0.5010.45	0.6010.45	2.70	4.05	0.20	0.0510.45	
L50	3.81±0.30	3.00±0.15	1.80±0.15	0.50±0.15	0.60±0.15	2.70	1.05	0.30	0.95±0.15	
SR1216	2 04 10 20	2 0010 45	4 0010 45	0.5010.45	0.6010.45	2.70	4.05	0.20	0.0510.45	
1L0	3.81±0.30	3.00±0.15	1.80±0.15	0.50±0.15	0.60±0.15	2.70	1.05	0.30	0.95±0.15	
SR1216	2 01+0 20	2 0010 45	1 0010 15	0.5010.45	0.6010.15	2.70	1.05	0.30	0.0540.45	
2L0	3.81±0.30	3.00±0.15	1.80±0.15	0.50±0.15	0.60±0.15	2.70	1.05	0.30	0.95±0.15	

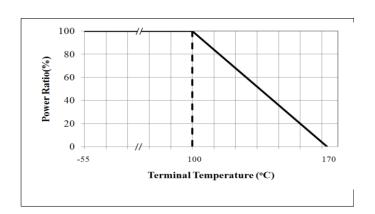
#### **Features**

- ♦ 3W~5W permanent power, Inductance<3nH
- ♦ Internal heat resistance <15K/W
- ◆ Lead free, RoHs compliant for global applications and halogen free

## **Application**

- Power modules
- ◆ Frequency converters
- ◆ Current sensor for power hybrid sources
- ♦ High current for automotive

## **Derating Curve**





Document No: SR1216STD001A



# **Current Sensing Shunt Resistor**

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#### **Part Numbers**

<u>SR 1216 E F H 1L00</u>

(1) (2) (3) (4) (5) (6)

(1)Series Name: SR (Shunt Resistor)

(2) Chip size: 1216(inch)

(3)Packaging Material: Emboss

(4) Resistance Tolerance: ±1% (F), ±5% (J)

(5)Power rating: L=5W, H=3W

(6)Resistance Code: EX: 1L0 means 1.0m  $\Omega$  , etc.

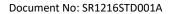
## **Electrical Specification**

Item	Power Rating	Resistance Range(m $\Omega$ )	Operation Temp. Range	TCR (PPM/°C)	Resistance Material
SR1216	5W	0.2	-55 <b>~</b> +170°ℂ	±150	MnCuSn
SR1216	5W	0.5	-55 <b>~</b> +170°ℂ	±50	MnCuSn
SR1216	3W	1.0	-55~+170°C	±50	MnCu
SR1216	2W	2.0	-55 <b>~</b> +170°ℂ	±50	MnCuNi

#### **Performances**

#### **Environmental Performance**

No.	Item	Test Condition	Specification
1	Short Time Overload	Loading 5 times rate power 5sec	ΔR: ±1%
2	Temperature Coefficient of Resistance (T.C.R.)	-20°C /+125°C. (JIS-C5202-5.2) $TCR \text{ (ppm/°C)} = \frac{\Delta R}{R \times \Delta t} \times 10^{6}$	Refer to electrical specification.
3	Moisture Resistance	The specimens shall be placed in a chamber and subjected to a relative humidity of 90~98% percent and a temperature of 25°C / 65°C 10 cycles (MIL-STD-202, Method 106)	ΔR: ±1%





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4	High Temperature Exposure	The ship (mounted on board) is exposed in the heat chamber 170 $^{\circ}$ C for 1000 hrs. (JIS-C5202-7.2)	ΔR: ±1%
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#### **Performances**

#### **Environmental Performance**

No.	Item	Test Condition	Specification
5	Load Life	Apply rated power for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±1%
6	Rapid change of temperature	The chip (mounted on board) is exposed, -20±3°C (30min.)/+125±2°C (30min.) for 1000 cycles.  The following conditions as the following figure.  (JIS-C5202-7.4)  Ambient temperature 30 min. 30 min. 30 min. 2~3 min. 2~3 min. 2~3 min.	ΔR: ±1%

#### Remark:

All Reliability test should follow De-rating curve , terminal temperature of component should be below  $100\,^{\circ}$  .

#### **Function Performance**

No.	Item	Test Condition	Specification
2	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath $235\pm5^{\circ}\mathbb{C}$ for $2\pm0.5$ sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5 202-6.11)  Molten solder  Specimen Shid $h = 10 \text{ mm}$ $H = 10 \text{ mm}$ min.	Solder shall be covered 95% or more of the electrode area.

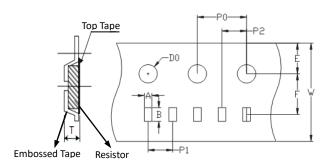


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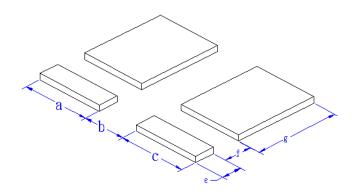
## **Tape Packaging Specifications**

◆Embossed Plastic Tape Specifications



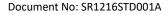
Туре		Carrier Dimensions (mm)								
Турс	Α	В	Е	F	W	P0	P1	P2	D0	Т
SR1216	3.3±0.1	4.2±0.1	2.64 <u>±</u> 0.1	5.5 <u>±</u> 0.1	12.0±0.2	4.0±0.1	8.0±0.1	2.0±0.05	1.5±0.1	2.1±0.1

## **Recommended Pad Layout**



Туре	Dimensions(mm)							
(inch size)	а	b	С	е	f	g		
SR1216	1.50±0.10	0.60±0.10	1.50±0.10	0.70±0.10	0.50±0.10	2.95±0.10		

Note. pad size, solder insufficient, excessive solder, solder void and component shifted will affect the resistance accuracy after IR reflow. Circuit calibration is a must to be done by functional test.





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#### **Packaging**

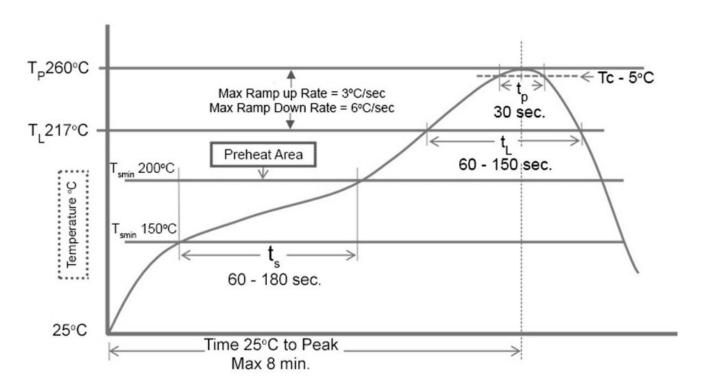
Size EIA (EIAJ)	1216
Standard Packing Quantity (pcs /Reel)	3,000

#### **Storage Conditions**

Temperature: 22~28°C, Humidity: 40~75%

#### **Soldering Recommendations**

- ◆ Peak reflow temperatures and durations:
  - IR Reflow Peak =  $260^{\circ}$ C max for 10 sec
  - Not suitable for wave soldering
- ◆ Recommended IR Reflow Profile:



#### **ECN**

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in Approval Sheet.